



#51A
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Roberts

Express Mail No.: EL 451 599 037 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
CHEAH

Serial No.: 09/863,651

Group Art Unit: 2827

Filed: May 22, 2001

Examiner: James M. Mitchell

For: INTEGRATED CIRCUIT PACKAGE
AND PROCESS FOR FORMING THE
SAME

Attorney Docket No.: 9818-052-999

RESPONSE TO OFFICIAL ACTION MAILED JUNE 6, 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicants submit the following amendments and remarks in response to the Office Action mailed June 6, 2002, in the above identified application.

A Petition for Extension of Time is enclosed requesting that the time for filing a Response to the Office Action be extended for a period of three months from September 6, 2002 to and including December 6, 2002.

Please amend the application as follows:

In the Claims:

Following is a list of all pending claims.

Marked up versions of all revised claims, showing insertions and deletions, are included in Appendix A.

1. (Amended) An integrated circuit package, comprising:
a substrate having a center region and a peripheral region;
a semiconductor die positioned on the center region of the substrate, the semiconductor die having a bond pad;
a lead finger mounting ring positioned on the peripheral region of the substrate;

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